

SOT619-17(D)

plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank, 48 terminals; 7 mm x 7 mm x 0.85 mm body

23 October 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-09-2018
Manufacturer package code	98ASA01307D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	7	-	mm
package width	-	7	-	mm
package height	-	0.85	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

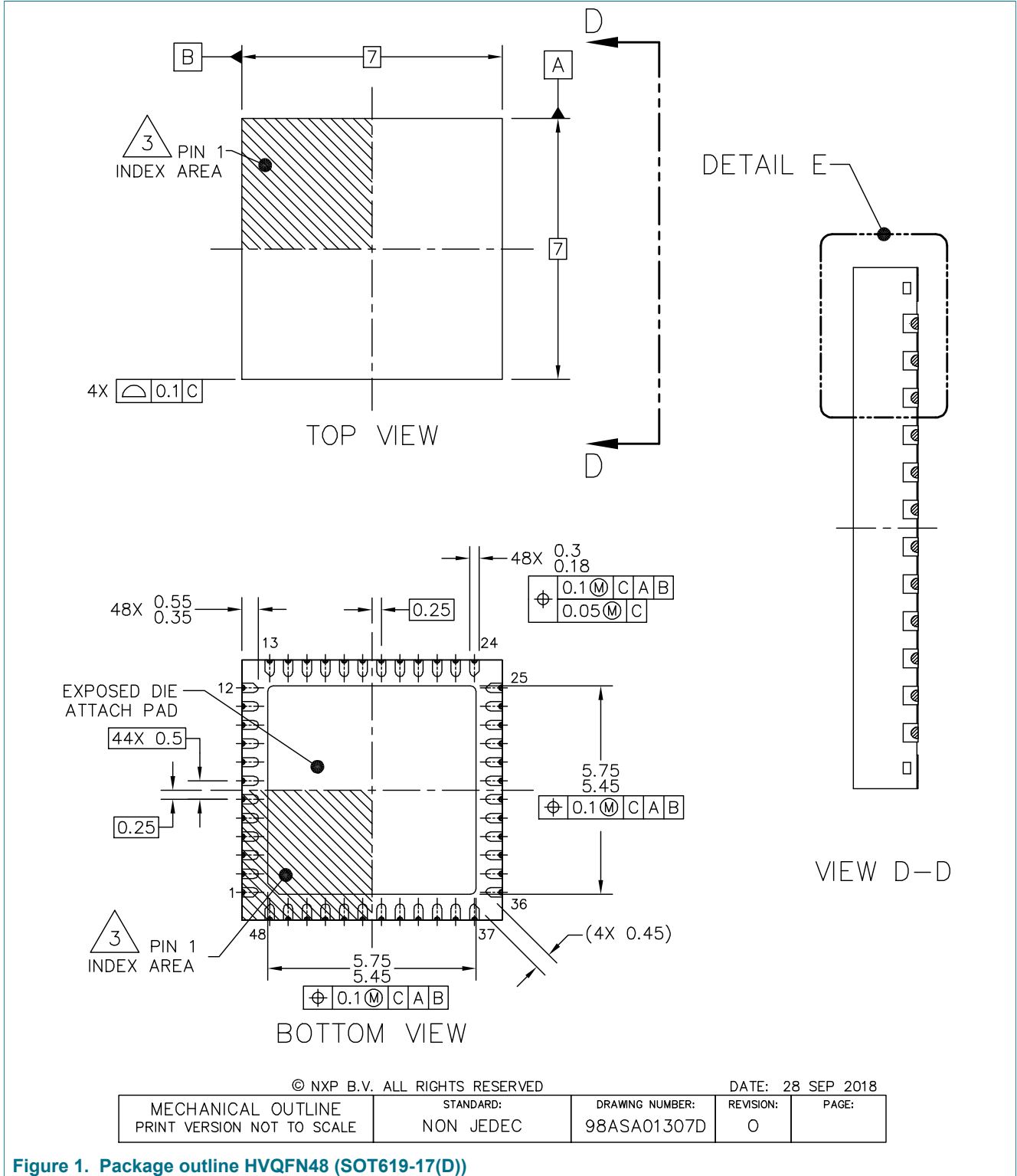


Figure 1. Package outline HVQFN48 (SOT619-17(D))

plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank, 48 terminals;
7 mm x 7 mm x 0.85 mm body

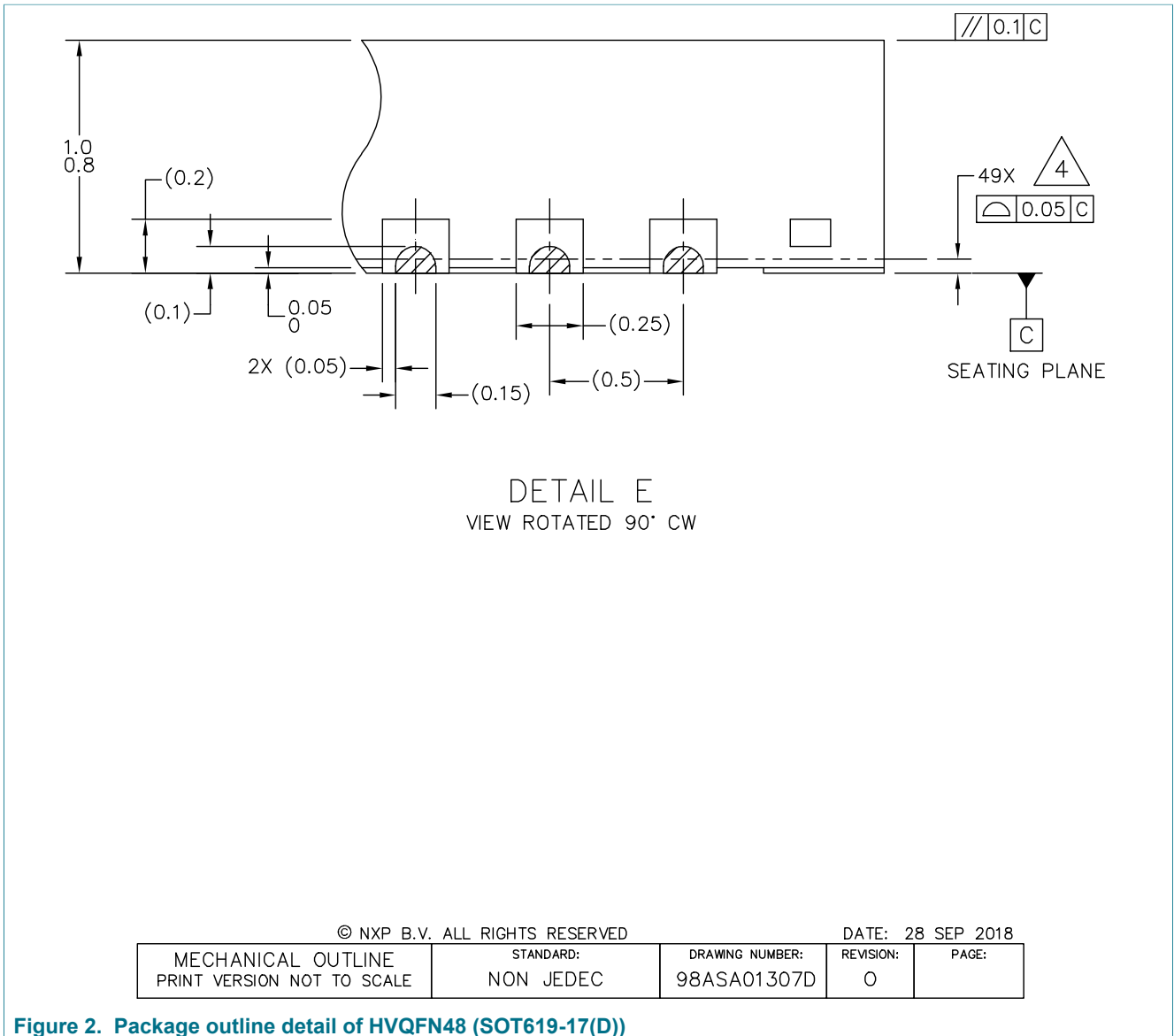
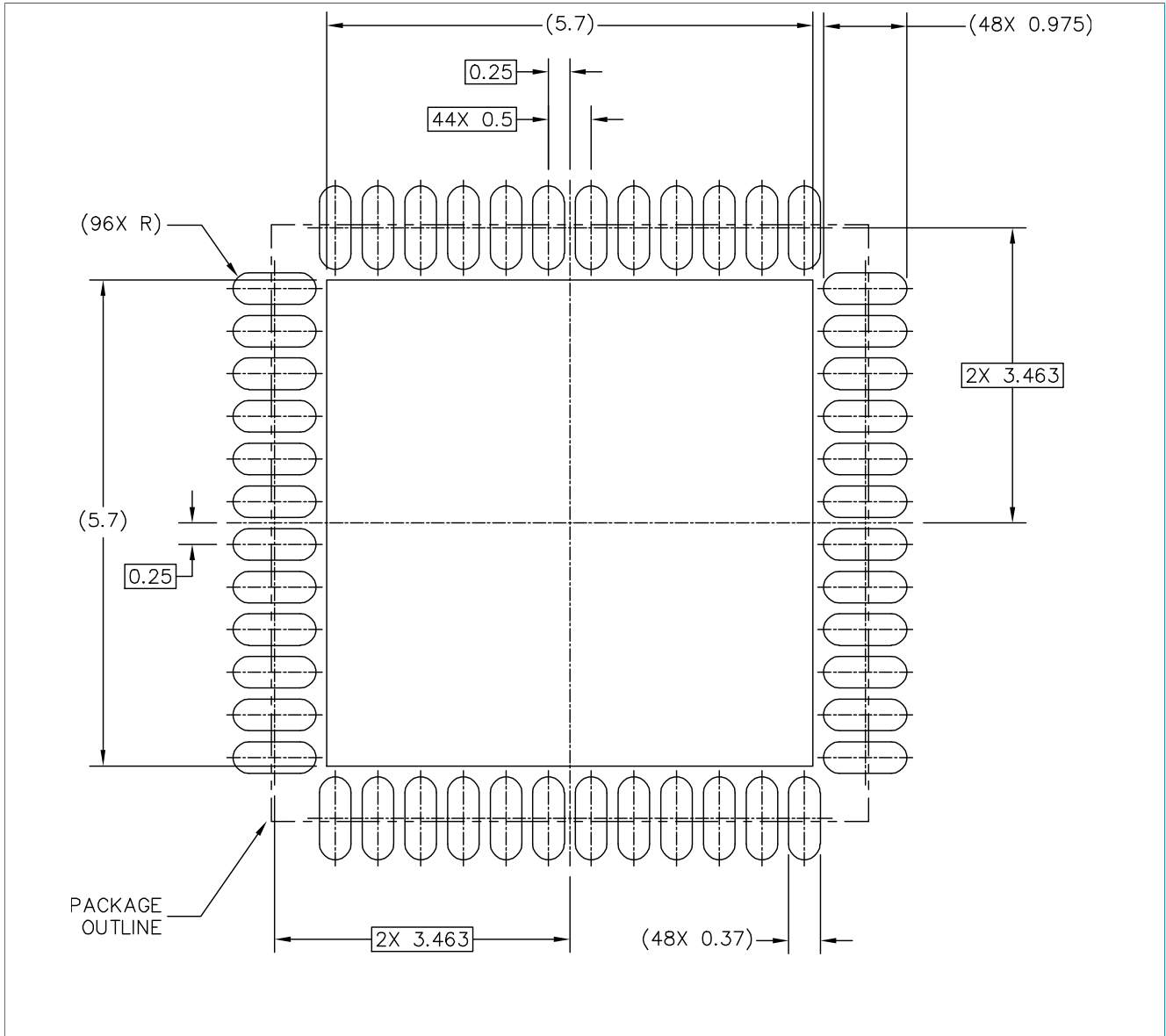


Figure 2. Package outline detail of HVQFN48 (SOT619-17(D))

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3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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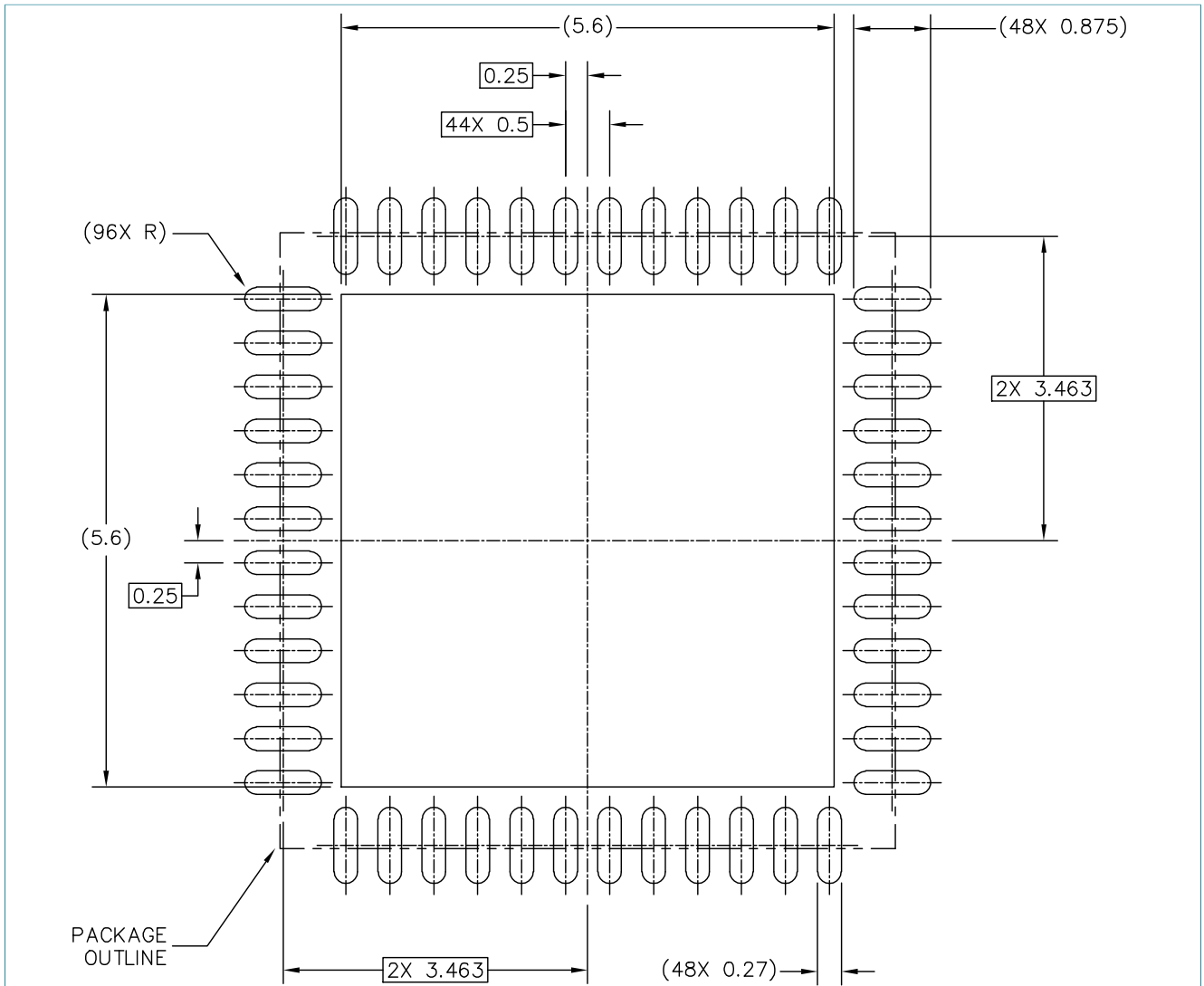
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Figure 3. Reflow soldering footprint part1 for HVQFN48 (SOT619-17(D))

plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank, 48 terminals;
7 mm x 7 mm x 0.85 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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Figure 4. Reflow soldering footprint part2 for HVQFN48 (SOT619-17(D))

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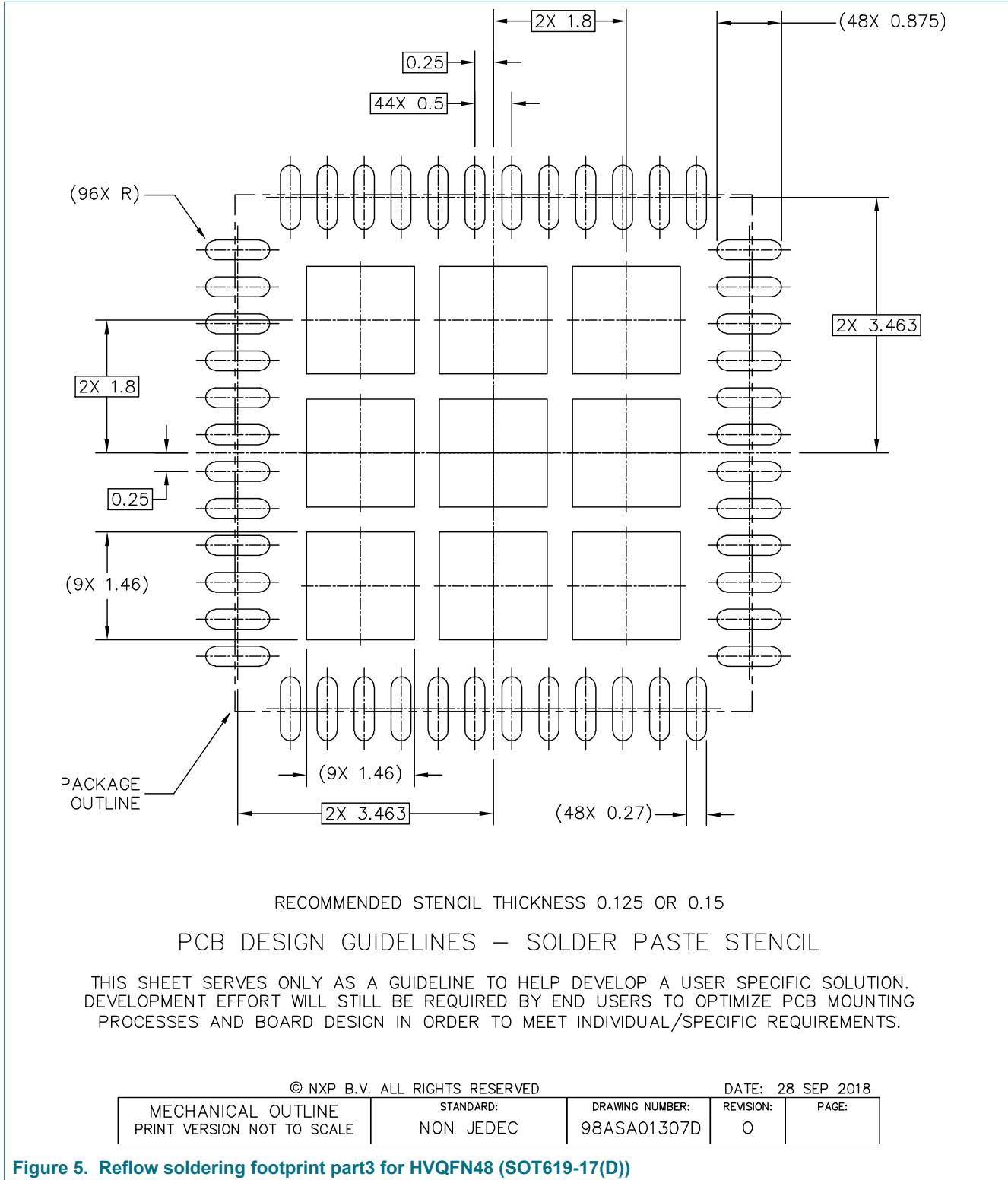


Figure 5. Reflow soldering footprint part3 for HVQFN48 (SOT619-17(D))

plastic thermal enhanced very thin quad flat package; no leads; 0.1 dimple wettable flank, 48 terminals;
7 mm x 7 mm x 0.85 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.25 MM.

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Figure 6. Package outline note HVQFN48 (SOT619-17(D))

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4 Legal information

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